

Application Data Sheet

Application Information

Application Number:: 10681583

Filing Date:: 10/08/2003

Application Type:: Regular

Subject Matter:: Utility

Title:: Semiconductor multi-package module having

inverted second package stacked over die-down

die-up flip-chip ball grid array (BGA) package

Attorney Docket Number:: CPAC 1029-5 D3

Total Drawing Sheets:: 20

Small Entity?:: No

Applicant Information

Applicant Authority Type: Inventor

Primary Citizenship Country: US

Status: Full Capacity

Given Name: Marcos

Family Name: Karnezos

City of Residence: Palo Alto

State or Province of Residence: CA

Country of Residence: US

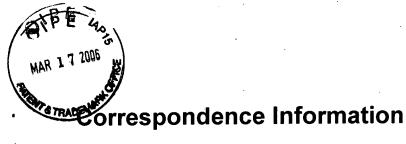
Street of mailing address: 535 Lytton Avenue

City of mailing address: Palo Alto

State or Province of mailing address: CA

Country of mailing address: US

Postal or Zip Code of mailing address: 94301



Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470		
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non-Provisional of	60/417,277	October 8, 2002
This Application	Non-Provisional of	60/460,541	April 4, 2003
This Application	Continuation-in-Part of	10/618,933	July 14, 2003
10/618,933	Non-Provisional of	60/460,541	April 4, 2003

Assignee Information

Assignee name::

ChipPAC, Inc.

Street of mailing address::

47400 Kato Road

City of mailing address::

Fremont

State or Province of mailing address::

CA

Country of mailing address::

US

Postal or Zip Code of mailing address:: 94538